

OCT 19 2006

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

In re Application of

Blaine J. Thurgood

Serial No. 10/685,312

Filed: October 14, 2003

For:

INTERPOSER SUBSTRATES WITH

MULTI-SEGMENT INTERCONNECT:
SLOTS, SEMICONDUCTOR DIE:
PACKAGES INCLUDING SAME,
SEMICONDUCOR DIE FOR USE:
THEREWITH AND METHODS OF:

FABRICATION

WITHDRAWAL FROM

ISSUE

The purpose of this communication is to inform you that the above-identified application is being withdrawn from issue pursuant to 37 CFR 1.313.

The application is being withdrawn to permit reopening of prosecution. The reasons therefor will be communicated to you by the examiner.

PTO records reveal that the issue fee has not been paid. If the issue fee has been submitted, the applicant may request a refund or may request that the fee be credited to a deposit account. However, applicant may wait until the application is either again found allowable or held abandoned. If the application is allowed, upon receipt of a new Notice of Allowance and Issue Fee Due, applicant may request that the previously submitted issue fee be applied toward payment of the issue fee in the amount identified on the new Notice of Allowance and Issue Fee Due. If the application is abandoned, applicant may request either a refund or a credit to a deposit account.

The application is being forwarded to the examiner for prompt action.

Frederick R. Schmidt, Director

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